Smart Systems (SmaSys2021)

Guest Editors:

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Deadline for manuscript submissions:
closed (31 March 2022)

Message from the Guest Editors

Dear Colleagues,

We are planning to publish a Special Issue on "Smart Systems" related to the International Conference of Smart Systems Engineering (SmaSys2021, http://smasys.yz.yamagata-u.ac.jp/2021/) held on 7–8 October 2021 in Yonezawa, Japan. This Special Issue provides opportunities for collaboration across a wide range of fields and technologies related to emerging smart systems. Smart systems regard broad scientific and engineering fields. They include organic materials, organic electronics, organic devices, biomaterials, biomedical and biosystem engineering, electrical engineering and informatics, mechanical systems engineering, smart flexible structures and systems, green materials and their processing, tourism engineering with agriculture and foods, and new engineering education.

All the participants of SmaSys2021 and their colleagues—especially students—are encouraged to submit their works to this Special Issue.

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Prof. Dr. Go Matsuba
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Guest Editors

Special Issue

Editor-in-Chief

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Message from the Editor-in-Chief

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